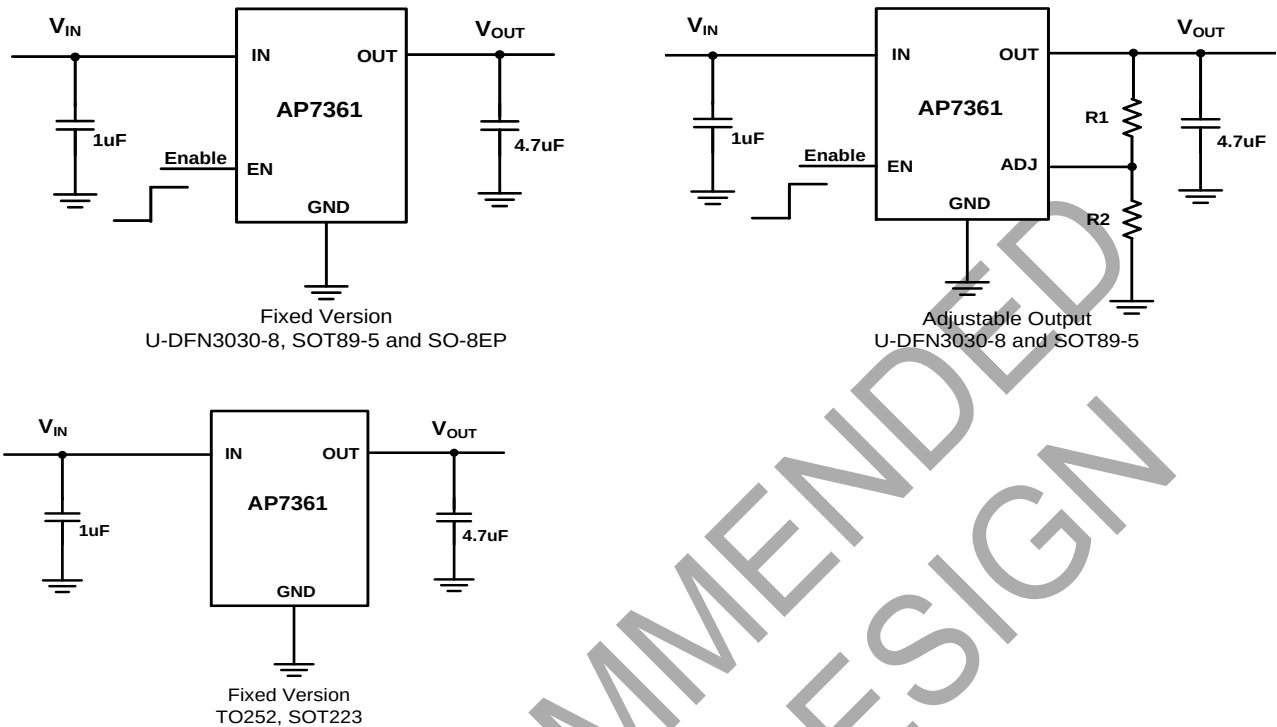


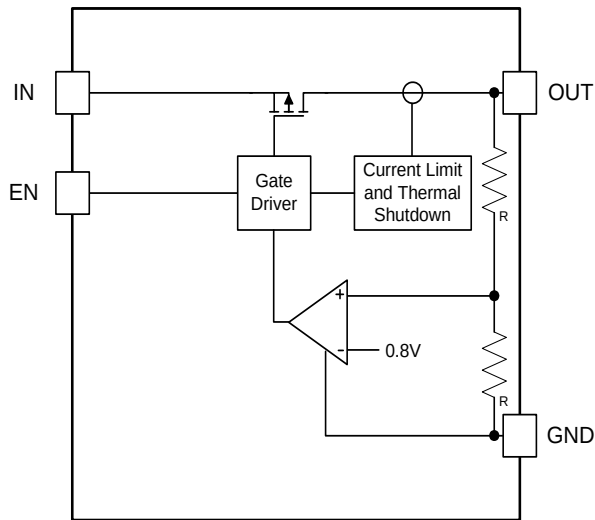
Typical Applications Circuit



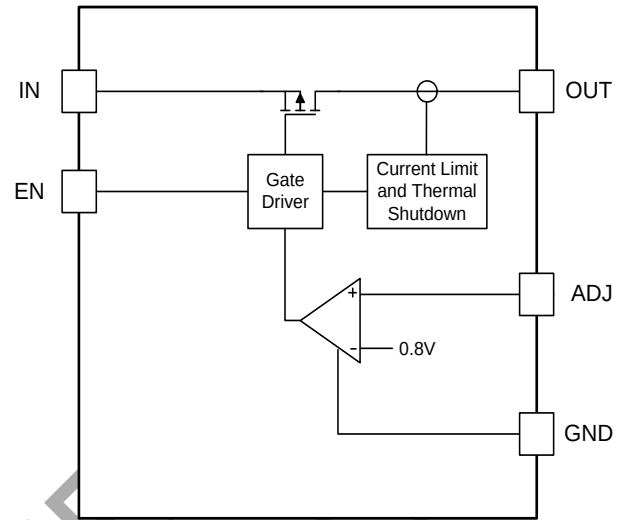
Pin Descriptions

Pin Name	Pin Number							Function
	U-DFN3030-8	SOT89-5	TO252	TO252R	SOT223	SOT223R	SO-8EP	
IN	8	4	1	3	1	3	8	The input of the regulator. Bypass to ground through at least 1 μ F ceramic capacitor.
OUT	1	5	3	2	3	2	1	The output of the regulator. Bypass to ground through at least 2.2 μ F ceramic capacitor. For improved ac load response a larger capacitor is recommended.
GND	4	2	2	1	2	1	4	Ground
ADJ	3	3	NA	NA	NA	NA	NA	Adjustable voltage version only – a resistor divider from this pin to the OUT pin and ground sets the output voltage.
EN	5	1	NA	NA	NA	NA	2	Enable input, active high
NC	2, 6, 7	NA	NA	NA	NA	NA	3, 5, 6, 7	No connection

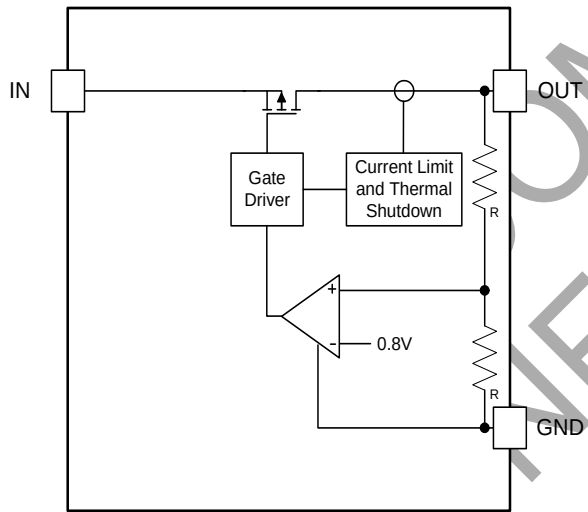
Functional Block Diagram



Fixed Version U-DFN3030-8, SOT89-5 and SO-8EP



Adjustable Version U-DFN3030-8 and SOT89-5



Fixed Version
TO252, SOT223

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Ratings	Unit
ESD HBM	Human Body Model ESD Protection	> 2	KV
ESD MM	Machine Model ESD Protection (Note 5)	> 200	V
V _{IN}	Input Voltage	6.5	V
	OUT, ADJ, EN Voltage	V _{IN} +0.3	V
T _J	Operating Junction Temperature Range	-40 to +150	°C
T _{ST}	Storage Temperature Range	-65 to +150	°C
P _D	Power Dissipation (Note 4)	Internally limited by maximum junction temperature of +150°C	
P _D	Power Dissipation (Note 4)	U-DFN3030-8	1,700
		TO252	1,250
		SOT223	1,100
		SOT89-5	800
		SO-8EP	1,190

Notes: 4. Ratings apply to ambient temperature at +25°C.
5. ESD MM rating at 150V for EN pin.

Stresses greater than the 'Absolute Maximum Ratings' specified above, may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit
V _{IN}	Input Voltage	2.2	6.0	V
I _{OUT}	Output Current (Note 6)	0	1.0	A
T _A	Operating Ambient Temperature	-40	+85	°C

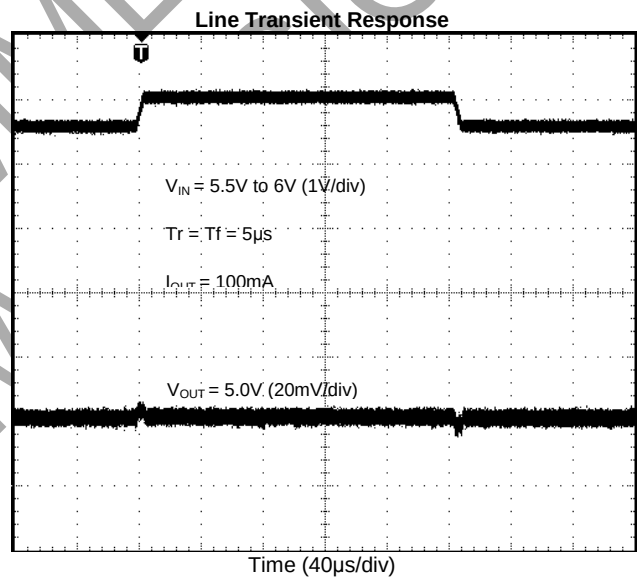
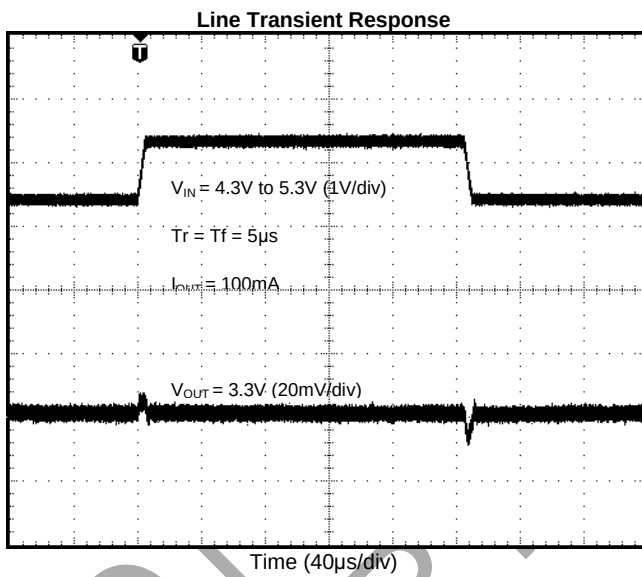
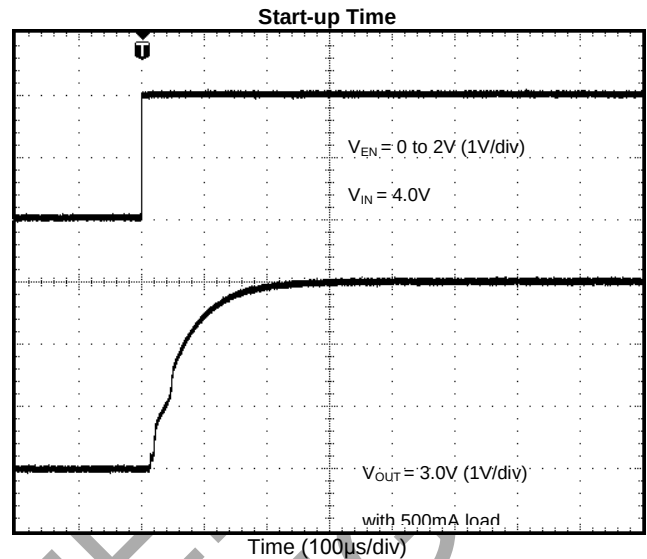
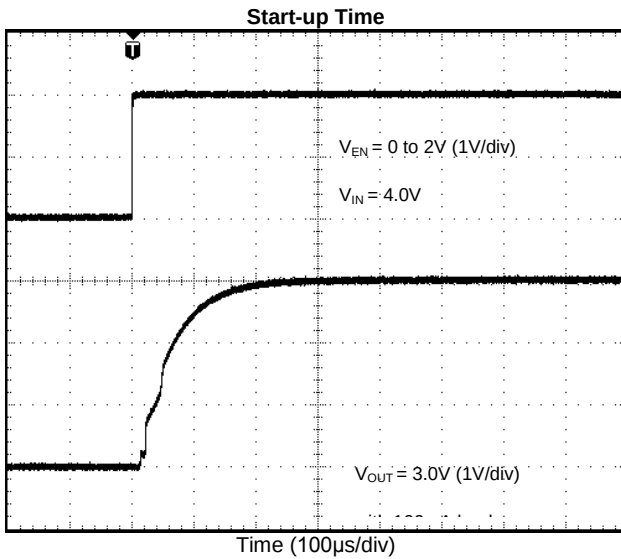
Note: 6. The device maintains a stable, regulated output voltage without a load current. When the output current is large, attention should be given to the limitation of the package power dissipation.

Electrical Characteristics (@T_A = +25°C, V_{IN} = V_{OUT} +1V, C_{IN} = 1μF, C_{OUT} = 4.7μF, V_{EN} = V_{IN} unless otherwise specified.)

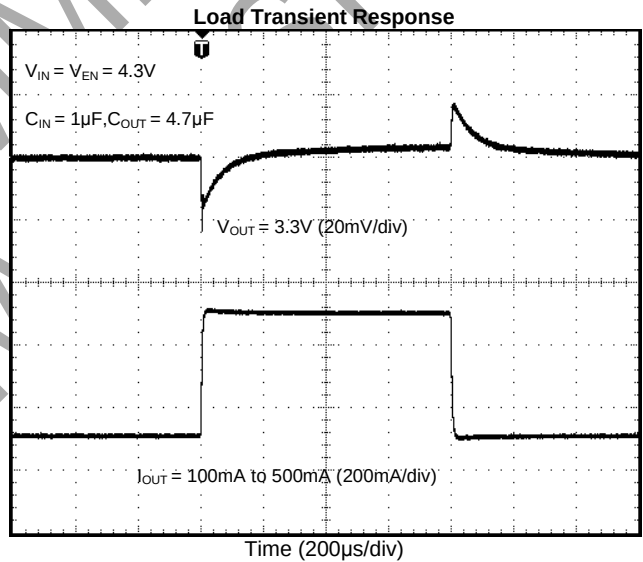
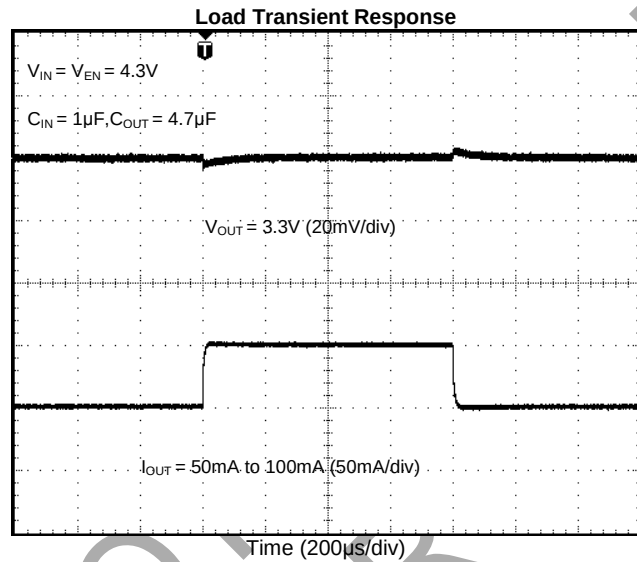
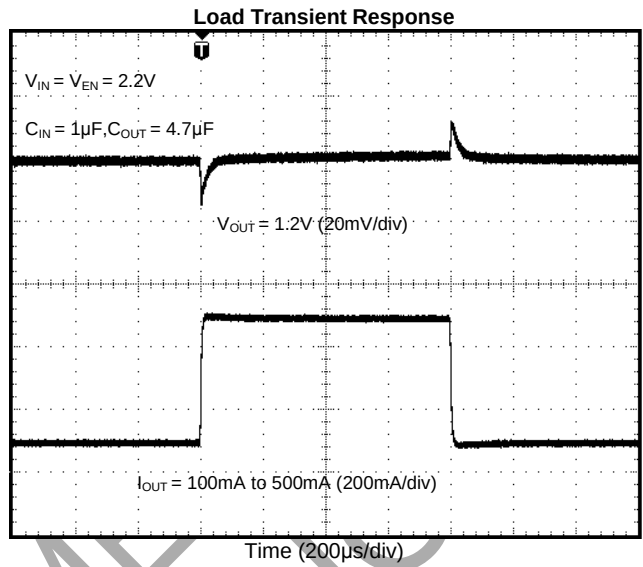
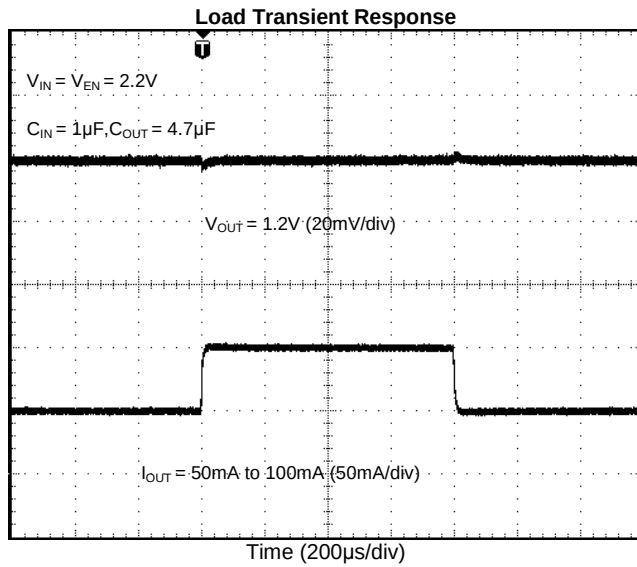
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V _{REF}	FB Reference Voltage	I _{OUT} = 10mA, T _A = +25°C		0.8		V
I _{ADJ}	ADJ Pin Leakage			0.1	0.5	μA
I _Q	Input Quiescent Current	Enabled, I _{OUT} = 0A		70	90	μA
I _{SHDN}	Input Shutdown Current	V _{EN} = 0V, I _{OUT} = 0A	-1	0.05	1	μA
V _{OUT}	Output Voltage Accuracy	I _{OUT} = 100mA, T _A = +25°C	-1		1	%
		I _{OUT} = 100mA, -40°C ≤ T _A ≤ +85°C	-2		2	
		Over V _{IN} , I _{OUT} , and T _A	-3	±0.5	3	
$\frac{\Delta V_{OUT}}{\Delta V_{IN} \times V_{OUT}}$	Line Regulation	V _{IN} = V _{OUT} +1V to 6V, I _{OUT} = 100mA		0.01	0.1	%/V
		T _A = +25°C -40°C ≤ T _A ≤ +85°C			0.2	
ΔV _{OUT} / V _{OUT}	Load Regulation	I _{OUT} from 1mA to 300mA	-1.0	0.5	1.0	%
		I _{OUT} from 1mA to 1A	-1.0	0.5	1.0	%
V _{DROPOUT}	Dropout Voltage (Note 7)	I _{OUT} = 300mA		150	200	mV
		I _{OUT} = 500mA		250	350	
		I _{OUT} = 1A		500	700	
V _{IL}	EN Input Logic Low Voltage		0		0.3	V
V _{IH}	EN Input Logic High Voltage		1.0		V _{IN}	V
I _{EN}	EN Input Leakage	V _{IN} = 6V, V _{EN} = 0V or 6V	-0.1	0.01	0.1	μA
I _{LIMIT}	Current Limit	V _{IN} = V _{OUT} +1V	1.1	1.5		A
I _{SHORT}	Short-Circuit Current	V _{IN} = V _{OUT} +1V, Output Voltage < 15% V _{OUT}		200		mA
PSRR	Power Supply Rejection Ratio (Note 8)	f = 1KHz, I _{OUT} = 100mA	60	65		dB
		f = 10KHz, I _{OUT} = 100mA		45		
t _{ST}	Start-Up Time	V _{OUT} = 3V, C _{OUT} = 1μF, R _L = 30Ω		200		μs
$\frac{\Delta V_{OUT}}{\Delta T_A \times V_{OUT}}$	Output Voltage Temperature Coefficient	I _{OUT} = 100mA, -40°C ≤ T _A ≤ +85°C		±130		ppm/°C
T _{SHDN}	Thermal Shutdown Threshold			150		°C
T _{HYS}	Thermal Shutdown Hysteresis			20		°C
θ _{JA}	Thermal Resistance Junction-to-Ambient	U-DFN3030-8 (Note 9)		70		°C/W
		TO252 (Note 9)		95		
		SOT223 (Note 9)		110		
		SOT89-5 (Note 9)		150		
		SO-8EP (Note 9)		100		

- Notes:
- Dropout voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value. This parameter only applies to output voltages above 1.5V since minimum V_{IN} = 2.2V.
 - For V_{IN} ≥ 2.5V and V_{IN} = V_{OUT} +1V. For V_{IN} < 2.5V, the PSRR performance may be reduced.
 - Test condition: DFN3030E-8, SO-8EP device mounted on 2"x2", FR-4 substrate PCB, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane. TO252 device mounted on 2"x2" FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. SOT223 the device is mounted on FR-4 substrate PC board, with minimum recommended pad layout. SOT89-5L device mounted on 1"x1" FR-4 substrate PC board, with minimum recommended pad layout.

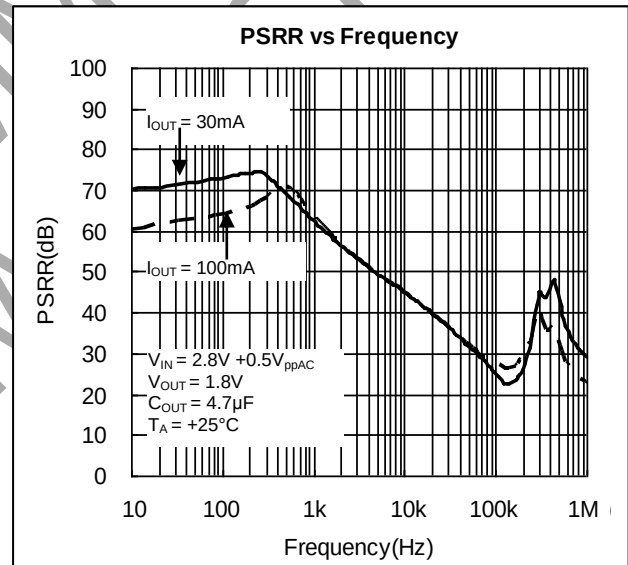
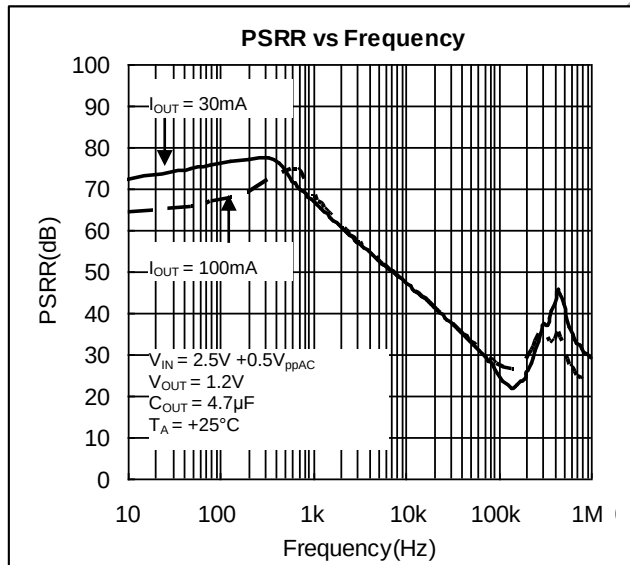
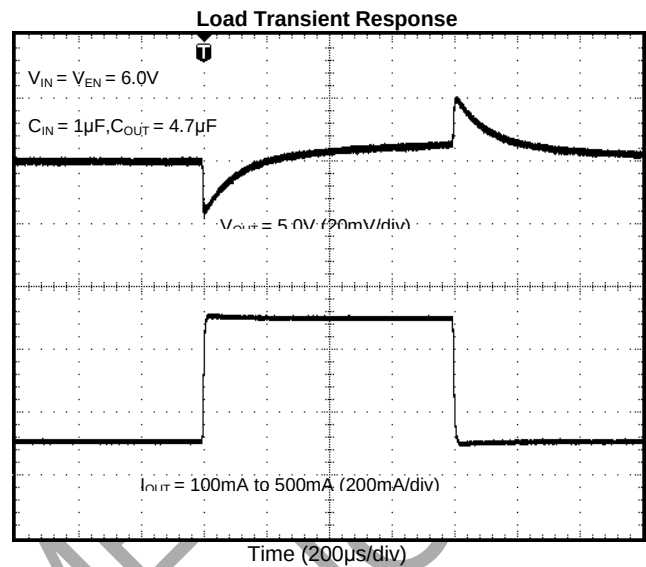
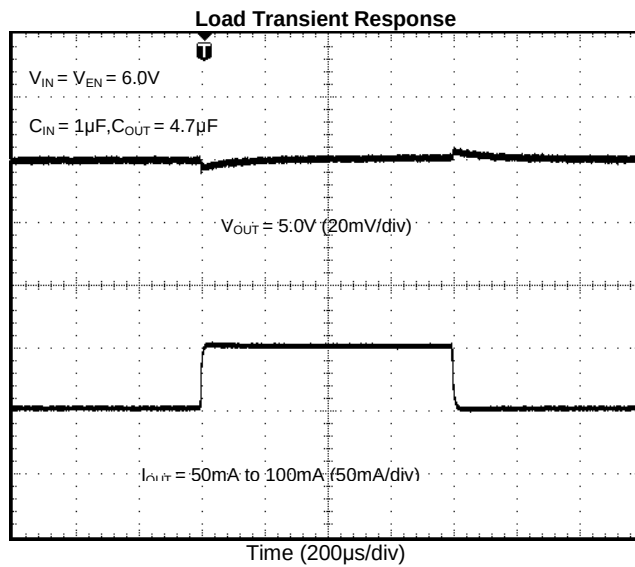
Typical Performance Characteristics



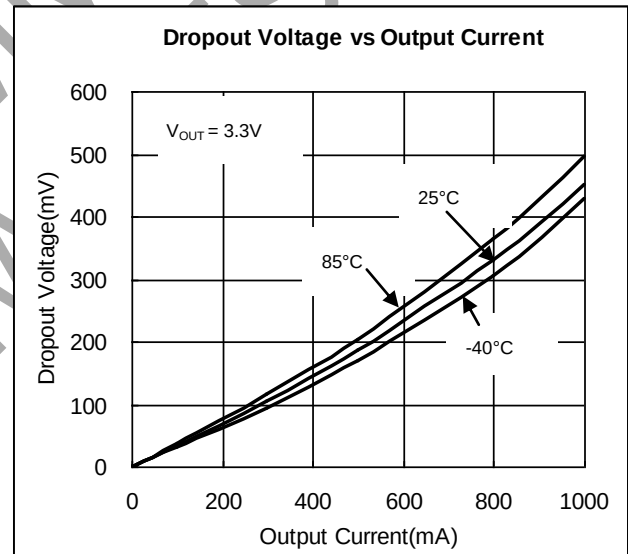
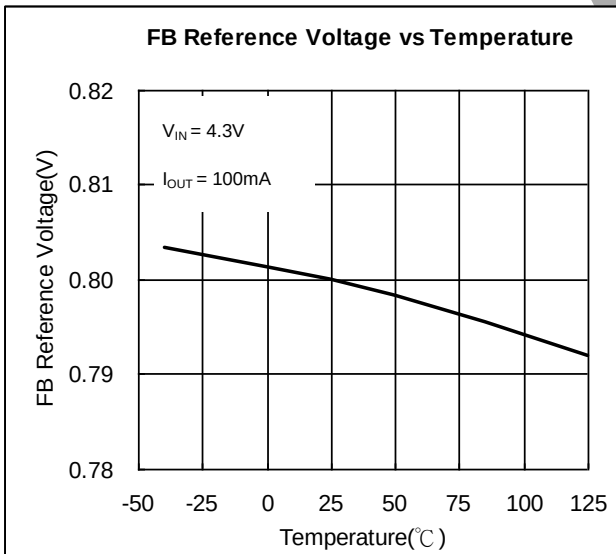
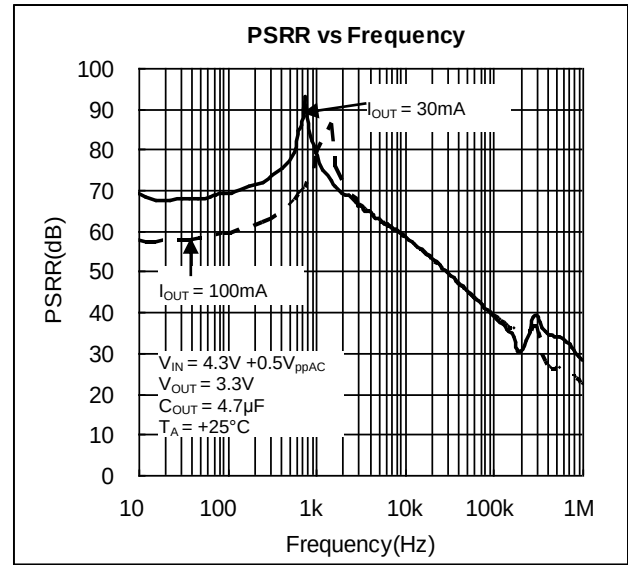
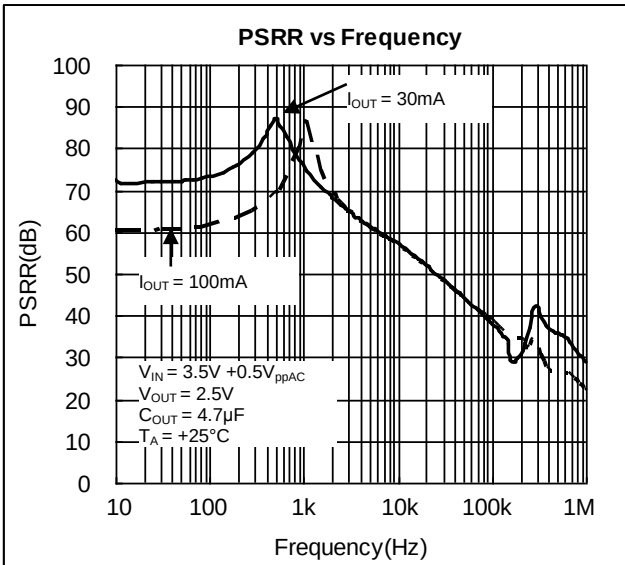
Typical Performance Characteristics (cont.)



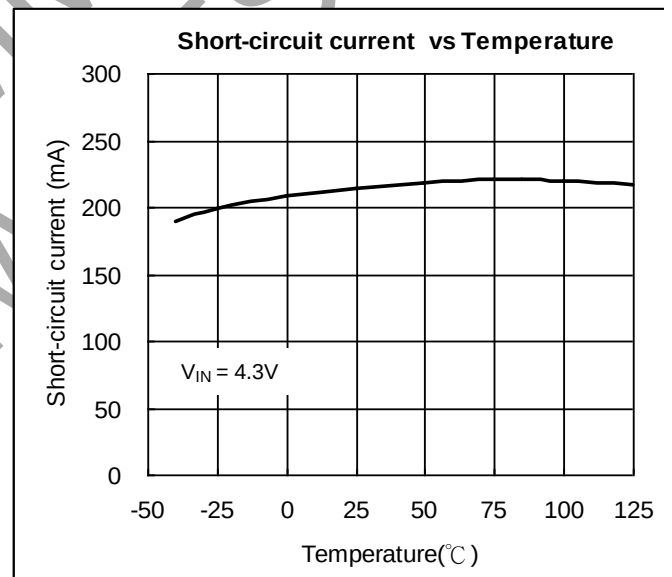
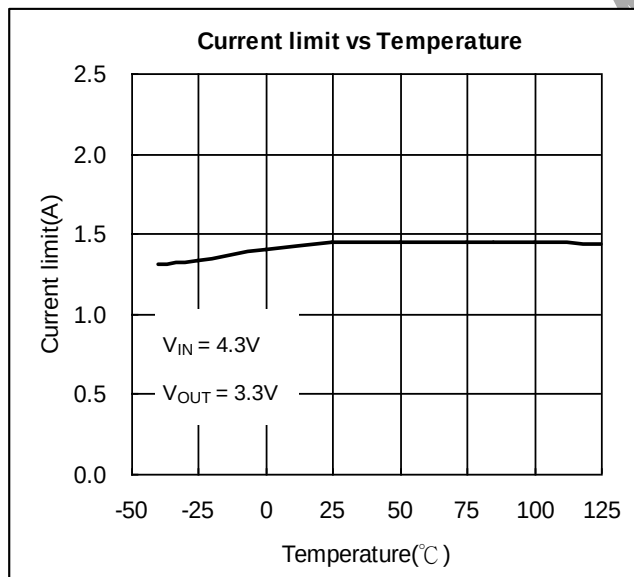
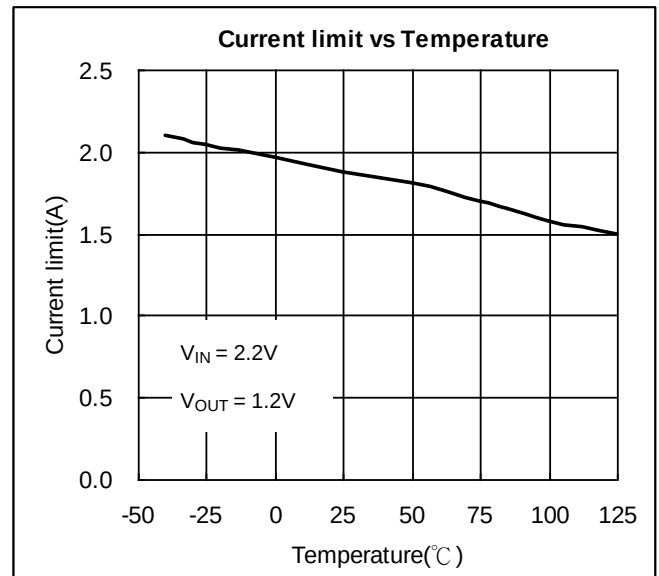
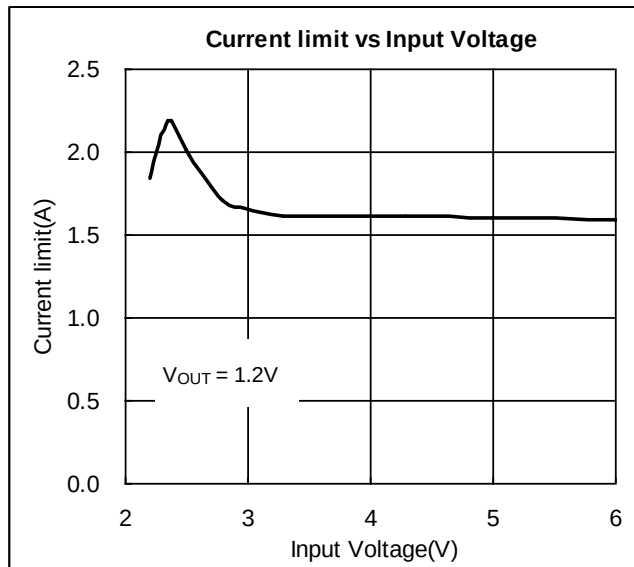
Typical Performance Characteristics (cont.)



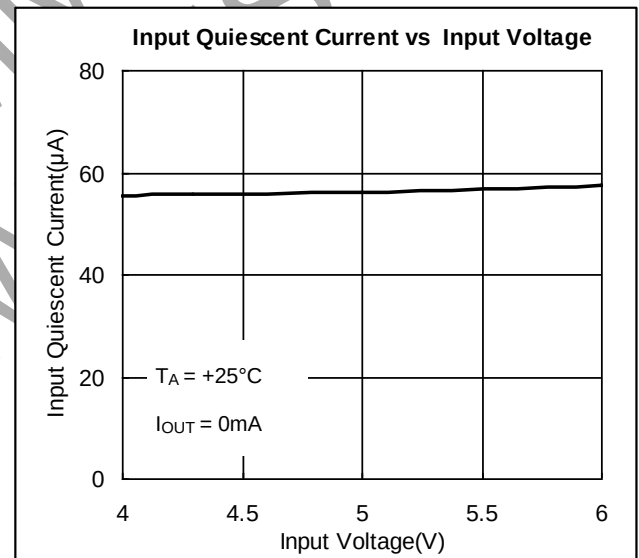
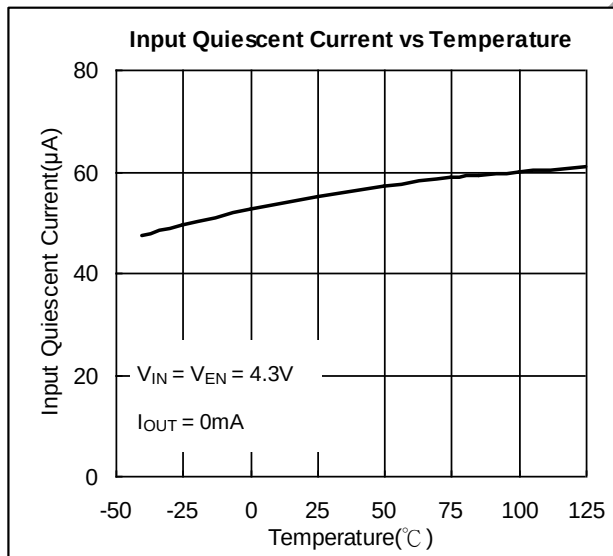
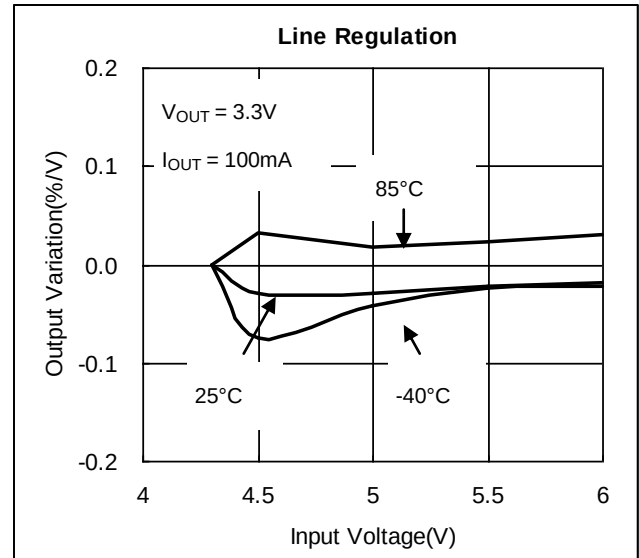
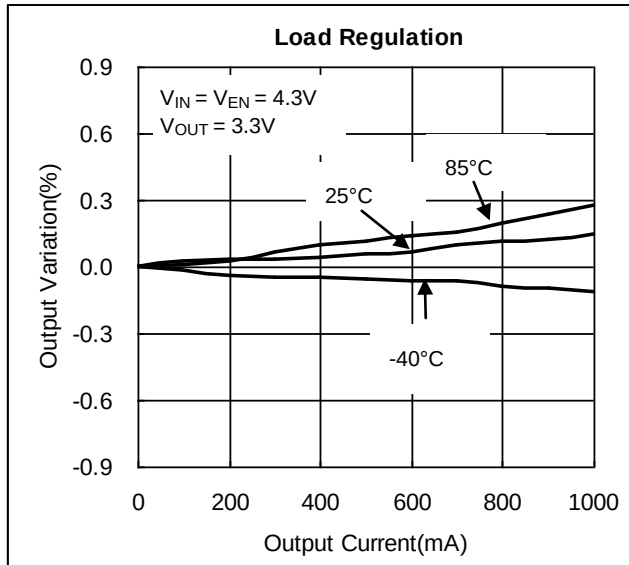
Typical Performance Characteristics (cont.)



Typical Performance Characteristics (cont.)



Typical Performance Characteristics (cont.)



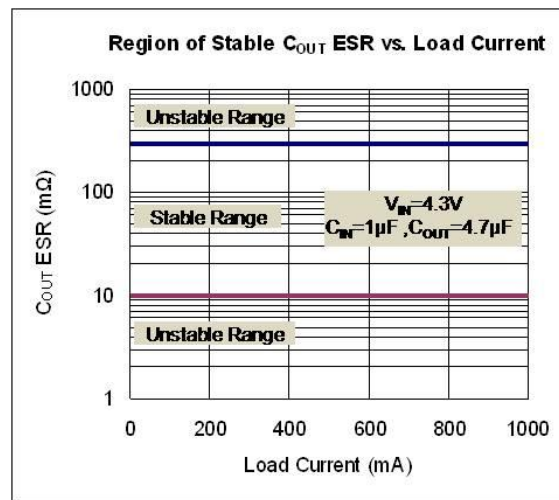
Application Information

Input Capacitor

A 1μF ceramic capacitor is recommended between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and reduce noise. For PCB layout, a wide copper trace is required for both IN and GND pins. A lower ESR capacitor type allows the use of less capacitance, while a higher ESR type requires more capacitance.

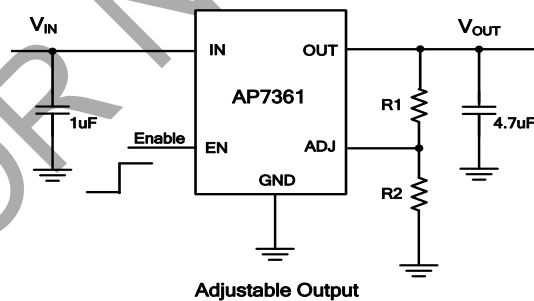
Output Capacitor

The output capacitor is required to stabilize and improve the transient response of the LDO. The AP7361 is stable with very small ceramic output capacitors. Using a ceramic capacitor value that is at least 2.2μF with $10\text{m}\Omega \leq \text{ESR} \leq 300\text{m}\Omega$ on the output ensures stability. Higher capacitance values help to improve line and load transient response. The output capacitance may be increased to keep low undershoot and overshoot. Output capacitor must be placed as close as possible to OUT and GND pins.



Adjustable Operation

Adjustable operation is not available in the SOT223 TO252 and SO-8EP package. The AP7361 provides output voltage from 0.8V to 5.0V through external resistor divider as shown below.



The output voltage is calculated by:

$$V_{OUT} = V_{REF} \left(1 + \frac{R_1}{R_2} \right)$$

Where $V_{REF} = 0.8\text{V}$ (the internal reference voltage)

Rearranging the equation will give the following that is used for adjusting the output to a particular voltage:

$$R_1 = R_2 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$$

To maintain the stability of the internal reference voltage, R₂ need to be kept smaller than 80kΩ.

Application Information

No Load Stability

Other than external resistor divider, no minimum load is required to keep the device stable. The device will remain stable and regulated in no load condition.

ON/OFF Input Operation

The ON/OFF feature is not available in the SOT223 and TO252 package.

The AP7361 is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to IN pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under V_{IL} and V_{IH} .

Current Limit Protection

When output current at OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to prevent overcurrent and to protect the regulator from damage due to overheating.

Short-Circuit Protection

When OUT pin is short-circuit to GND, short circuit protection will be triggered and clamp the output current to approximately 200mA. Full current is restored when the output voltage exceeds 15% of V_{out} . This feature protects the regulator from overcurrent and damage due to overheating.

Thermal Shutdown Protection

Thermal protection disables the output when the junction temperature rises to approximately +150°C, allowing the device to cool down. When the junction temperature reduces to approximately +130°C the output circuitry is enabled again. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the heat dissipation of the regulator, protecting it from damage due to overheating.

Ultra Fast Start-up

After enabled, the AP7361 is able to provide full power in as little as tens of microseconds, typically 200μs, without sacrificing low ground current. This feature will help load circuitry move in and out of standby mode in real time, eventually extend battery life for mobile phones and other portable devices.

Low Quiescent Current

The AP7361, consuming only around 70μA for all input range, provides great power saving in portable and low power applications.

Power Dissipation

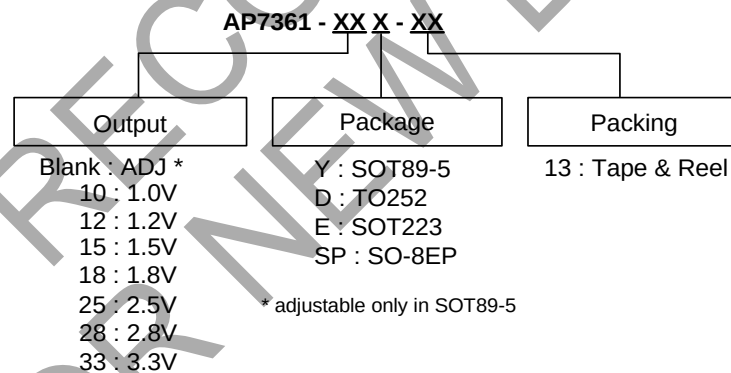
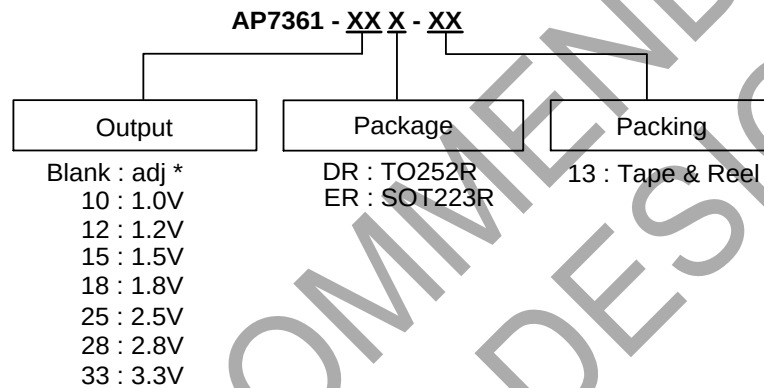
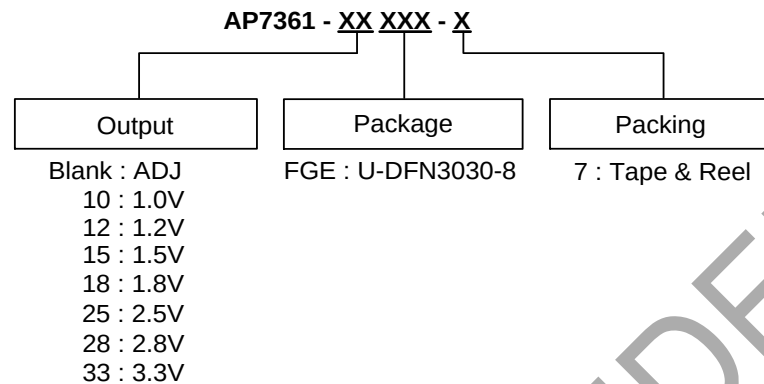
The device power dissipation and proper sizing of the thermal plane that is connected to the thermal pad is critical to avoid thermal shutdown and ensure reliable operation. Power dissipation of the device depends on input voltage and load conditions and can be calculated by:

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT}$$

The maximum power dissipation, handled by the device, depends on the maximum junction to ambient thermal resistance, maximum ambient temperature, and maximum device junction temperature, which can be calculated by the equation in the following:

$$P_{D(max@T_A)} = \frac{(+150^{\circ}\text{C} - T_A)}{R_{\theta JA}}$$

Ordering Information

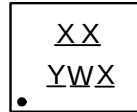


Part Number	Package Code	Packaging	7"/13" Tape and Reel	
			Quantity	Part Number Suffix
AP7361-XXFGE-7	FGE	U-DFN3030-8	3,000/Tape & Reel	-7
AP7361-XXY-13	Y	SOT89-5	2,500/Tape & Reel	-13
AP7361-XXD-13	D	TO252	2,500/Tape & Reel	-13
AP7361-XXDR-13	DR	TO252R	2,500/Tape & Reel	-13
AP7361-XXE-13	E	SOT223	2,500/Tape & Reel	-13
AP7361-XXER-13	ER	SOT223R	2,500/Tape & Reel	-13
AP7361-XXSP-13	SP	SO-8EP	2,500/Tape & Reel	-13

Marking Information

(1) U-DFN3030-8

(Top View)

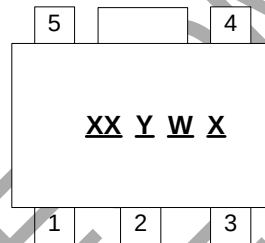


XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week
X : A~Z : Internal code

Device	Package	Identification Code
AP7361ADJ	U-DFN3030-8	PA
AP7361-10	U-DFN3030-8	PB
AP7361-12	U-DFN3030-8	PC
AP7361-15	U-DFN3030-8	PD
AP7361-18	U-DFN3030-8	PE
AP7361-25	U-DFN3030-8	PF
AP7361-28	U-DFN3030-8	PG
AP7361-33	U-DFN3030-8	PH

(2) SOT89-5

(Top View)



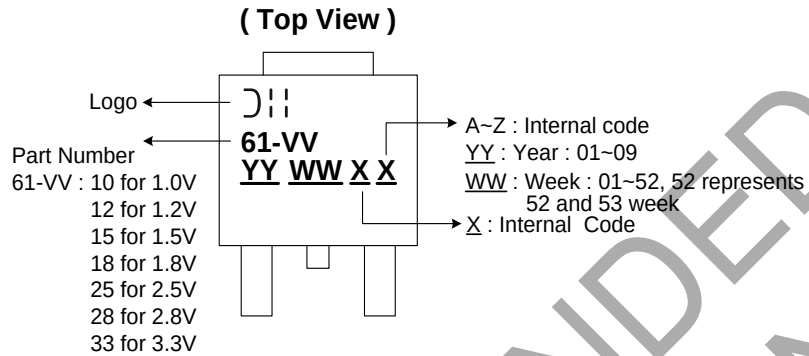
XX : Identification code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week;
z represents 52 and 53 week
X : A~Z : Internal code

Device	Package	Identification Code
AP7361ADJ	SOT89-5	PA
AP7361-10	SOT89-5	PB
AP7361-12	SOT89-5	PC
AP7361-15	SOT89-5	PD
AP7361-18	SOT89-5	PE
AP7361-25	SOT89-5	PF
AP7361-28	SOT89-5	PG
AP7361-33	SOT89-5	PH

Marking Information (cont.)

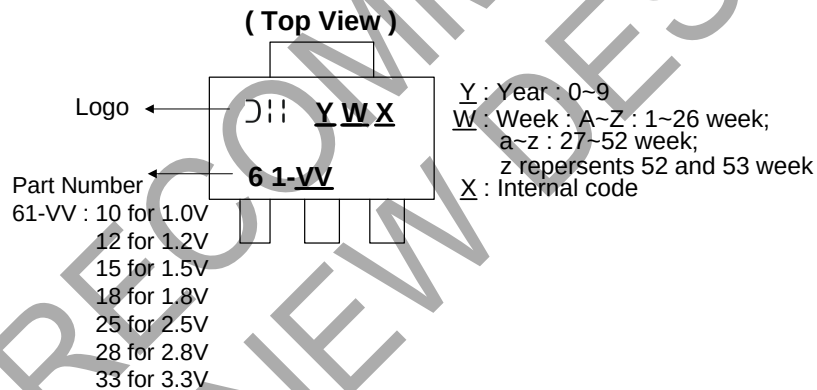
(3) TO252

Pin 1: V_{IN} , Pin 2: GND, Pin 3: V_{OUT}



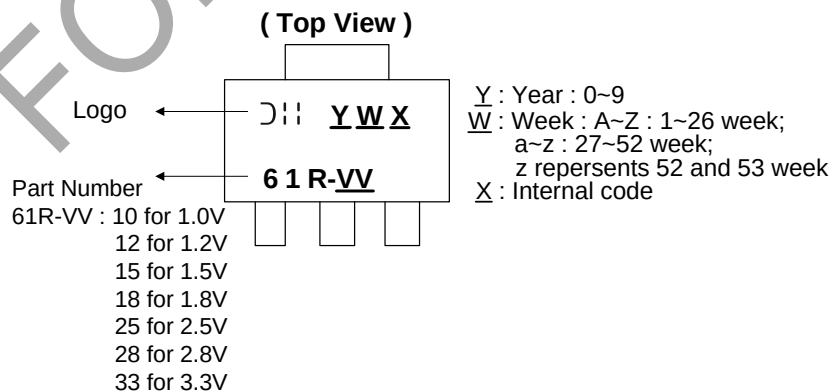
(4) SOT223

Pin 1: V_{IN} , Pin 2: GND, Pin 3: V_{OUT}



(5) SOT223R

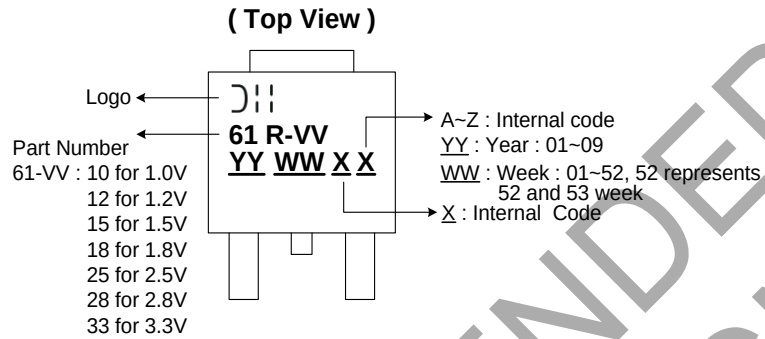
Pin 1: GND, Pin 2: V_{OUT} , Pin 3: V_{IN}



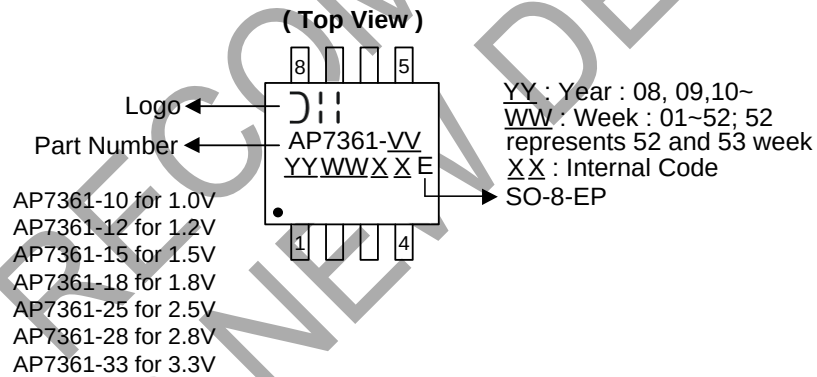
Marking Information (cont.)

(6) TO252-R

Pin 1: GND, Pin 2: V_{OUT} , Pin 3: V_{IN}



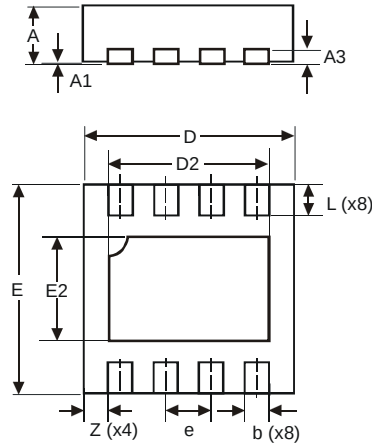
(7) SO-8EP



Package Outline Dimensions (All dimensions in mm.)

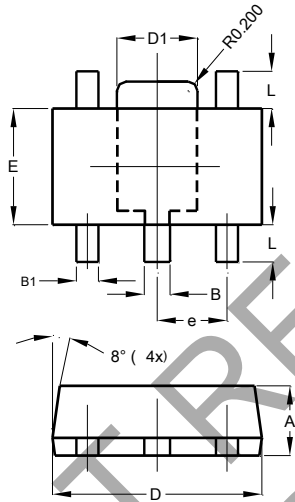
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1): U-DFN3030-8



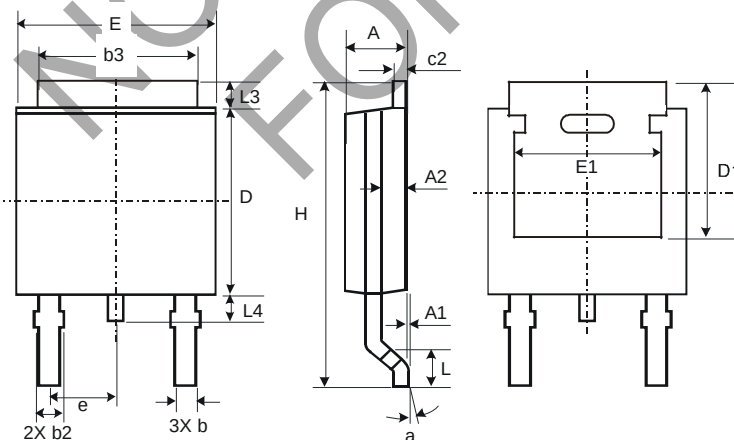
U-DFN3030-8 Type E			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0	0.05	0.02
A3	—	—	0.15
b	0.20	0.30	0.25
D	2.95	3.05	3.00
D2	2.15	2.35	2.25
E	2.95	3.05	3.00
e	—	—	0.65
E2	1.40	1.60	1.50
L	0.30	0.60	0.45
Z	—	—	0.40
All Dimensions in mm			

(2): SOT89-5



SOT89-5			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.50	0.62	0.56
B1	0.44	0.54	0.48
C	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
E	2.40	2.60	2.50
e	—	—	1.50
H	3.95	4.25	4.10
L	0.65	0.95	0.80
All Dimensions in mm			

(3): TO252

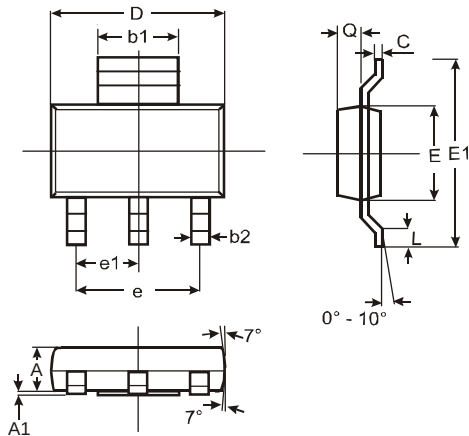


TO252			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	—	—
e	—	—	2.286
E	6.45	6.70	6.58
E1	4.32	—	—
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	—
All Dimensions in mm			

Package Outline Dimensions (cont.) (All dimensions in mm.)

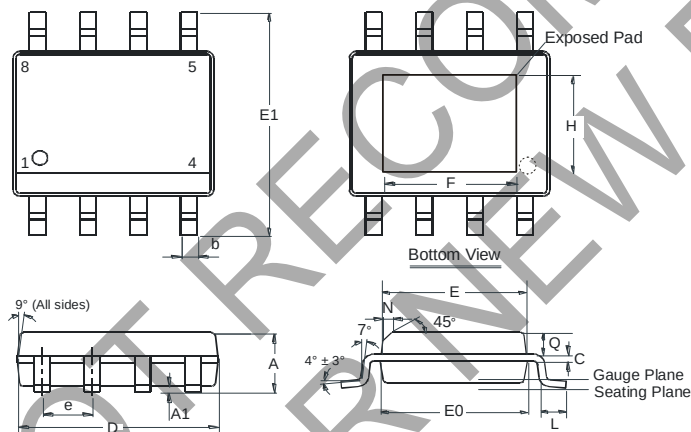
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4): SOT223 and SOT223R



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

(5): SO-8EP

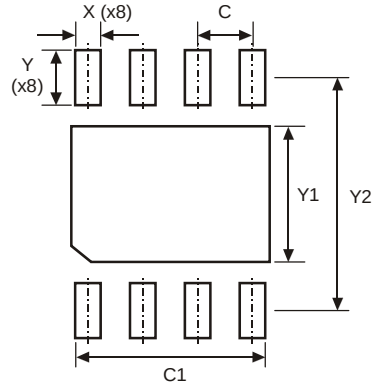


SO-8EP (SOP-8L-EP)			
Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.00	0.13	-
b	0.30	0.50	0.40
C	0.15	0.25	0.20
D	4.85	4.95	4.90
E	3.80	3.90	3.85
E0	3.85	3.95	3.90
E1	5.90	6.10	6.00
e	-	-	1.27
F	2.75	3.35	3.05
H	2.11	2.71	2.41
L	0.62	0.82	0.72
N	-	-	0.35
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

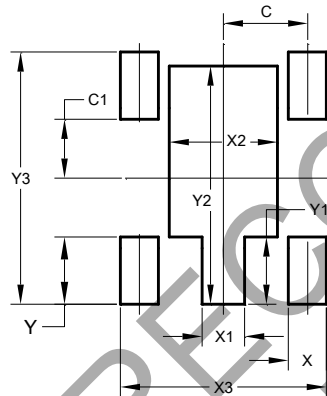
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1): U-DFN3030-8



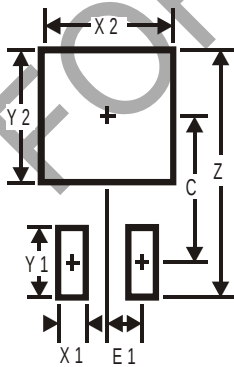
Dimensions	Value (in mm)
C	0.65
C1	2.35
X	0.30
Y	0.65
Y1	1.60
Y2	2.75

(2): SOT89-5



Dimensions	Value (in mm)
C	1.500
C1	1.050
X	0.680
X1	0.760
X2	1.930
X3	3.680
Y	1.200
Y1	1.200
Y2	4.250
Y3	4.500

(3): TO252

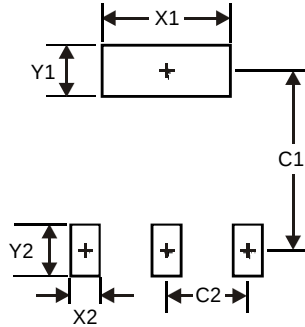


Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

Suggested Pad Layout (cont.)

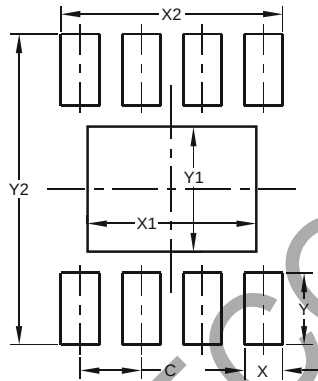
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4): SOT223 and SOT223R



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

(5): SO-8EP



Dimensions	Value(in mm)
C	1.270
X	0.802
X1	3.502
X2	4.612
Y	1.505
Y1	2.613
Y2	6.500

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